

TECHNICAL INFORMATION

TEMPORARY SOLDER RESIN PEEL OUT STD

DESCRIPTION

PEEL OUT STD is temporary latex-based Resin opportunely modified to ensure temporary protection from soldering some areas of printed circuit boards. Read the Material Safety Data Sheet before use.
The standard density at 20 C° is 0.94 Kg/L.

METHODS OF APPLICATION

Temporary solder resin PEEL OUT is a product ready to use and easy to use. The product is provided at the right density and viscosity for use.
For particular applications can be diluted with DI-water.
Apply the PEEL OUT STD on the area to protect with an automatic dispenser or with a brush or by hand.
Place a layer of approx. 1-2 mm.
Before welding, the product must be completely dry.

METHODS OF DRYING

At ambient temperature the drying time is approximately 8 h, in the oven at 80 ° C is about 5 minutes.
After welding the PEEL OUT STD can be removed with a slight manual pressure. The product is silicone, oils and acids free. It leaves no residue on protected areas, does not pollute the solder.

PACKAGING

The PEEL OUT STD is available in jars of 250cc and in tanks of 5 Kg.